

### Nch 100V 20A Power MOSFET

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	46m $\Omega$
I <sub>D</sub>	20A
$\overline{P_D}$	20W

### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

### Application

**Switching Power Supply** 

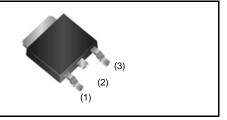
**Automotive Motor Drive** 

Automotive Solenoid Drive

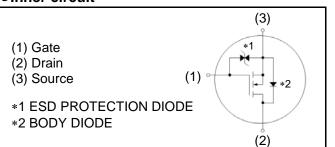
### **AEC-Q101 Qualified**

### Outline

CPT3 (SC-63) <SOT-428>



### •Inner circuit



Packaging specifications

- r dordaging opcomoducine						
Packaging	Taping					
Reel size (mm)	330					
Tape width (mm)	16					
Basic ordering unit (pcs)	2,500					
Taping code	TL					
Marking	201N10					
	Packaging Reel size (mm) Tape width (mm) Basic ordering unit (pcs) Taping code					

### • Absolute maximum ratings( $T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	100	V	
Continuous drain current	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±20	А
	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±10	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±80	А	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche energy, single pulse	E <sub>AS</sub> *3	14.6	mJ	
Avalanche current		I <sub>AR</sub> *3	10	А
B. F. C.	T <sub>c</sub> = 25°C	P <sub>D</sub>	20	W
Power dissipation	$T_a = 25$ °C	P <sub>D</sub>	0.85	W
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

Data Sheet

### ●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R <sub>thJC</sub>	-	-	6.25	°C/W

# ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	100	-	-	V
		$V_{DS} = 100V, V_{GS} = 0V$			1	
Zara gata valtaga drain avrent		$T_j = 25$ °C	-	-	ı	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V			100	
		T <sub>j</sub> = 125°C	-	-		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 1mA$	1.0	-	2.5	V
		$V_{GS} = 10V, I_D = 20A$	-	33	46	
Static drain - source		$V_{GS} = 4.0V, I_D = 20A$	-	36	50	O
on - state resistance	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 20A$		60	0.4	mΩ
		T <sub>j</sub> = 125°C	-	60	84	
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 20A$	15	30	1	S

2/12



## •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	2100	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	180	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	120	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 50V, V_{GS} = 10V$	-	100	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 10A	-	35	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L = 12\Omega$	-	150	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	100	-	

### **●Gate Charge characteristics**(T<sub>a</sub> = 25°C)

Doromotor	Symbol	Conditions	Values			Unit
Parameter Symb		Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*4}$	$V_{DD} \simeq 50V$	-	55	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 20A	-	5.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	12.5	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 30V$ , $I_D = 20A$	-	2.7	-	V

### ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit
Parameter Symb		TIDOI CONDITIONS		Тур.	Max.	
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	14	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 23 C	-	-	80	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 20A	-	65	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	144	-	μС

<sup>\*1</sup> Limited only by maximum temperature allowed.



<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  100 $\mu$ H,  $V_{DD}$  = 50V, Rg = 10 $\Omega$ , starting  $T_j$  = 25°C

<sup>\*4</sup> Pulsed

### •Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

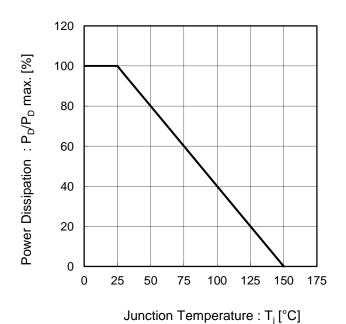
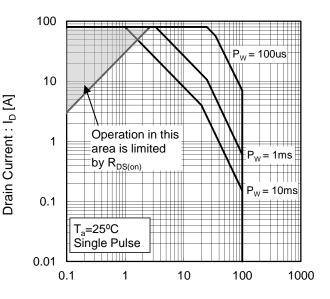
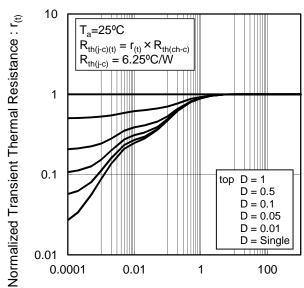


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width :  $P_W[s]$ 

4/12

### • Electrical characteristic curves

Fig.4 Avalanche Current vs Inductive Load

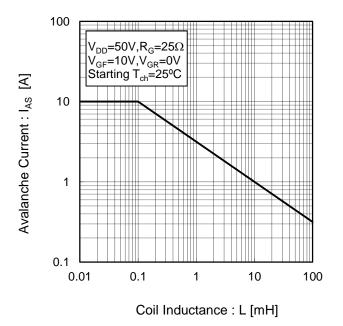
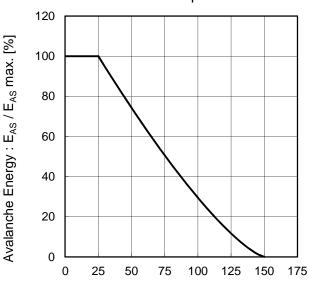
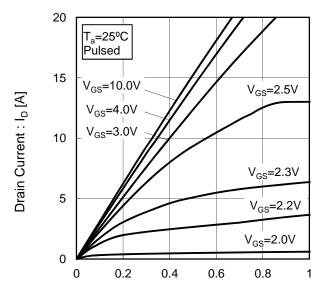


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



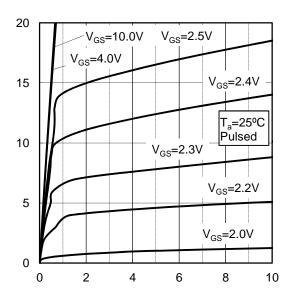
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current : I<sub>D</sub> [A]

### •Electrical characteristic curves

Fig.8 Breakdown Voltage vs. Junction Temperature 120 Normarize Drain - Source Breakdown Voltage  $V_{GS} = 0V$ 115  $I_D = 1 \text{mA}$ 110 105  $: V_{(BR)DSS}[V]$ 100 95 90 85 80 -50 0 50 100 150 Junction Temperature : T<sub>i</sub> [°C]

100 V<sub>DS</sub>= 10V 10 T<sub>a</sub>= 125°C T<sub>a</sub>= 75°C T<sub>a</sub>= 25°C T<sub>a</sub>= -25°C

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature 3.0  $V_{DS} = 10V$ Gate Threshold Voltage: V<sub>GS(th)</sub> [V] 2.5  $I_D = 1 \text{mA}$ 2.0 1.5 1.0 0.5 0.0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T<sub>i</sub> [°C]

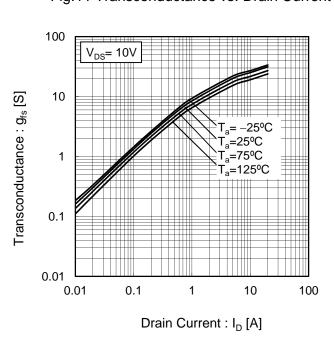


Fig.11 Transconductance vs. Drain Current

Gate - Source Voltage : V<sub>GS</sub> [V]

Data Sheet

### •Electrical characteristic curves

RSD201N10FRA

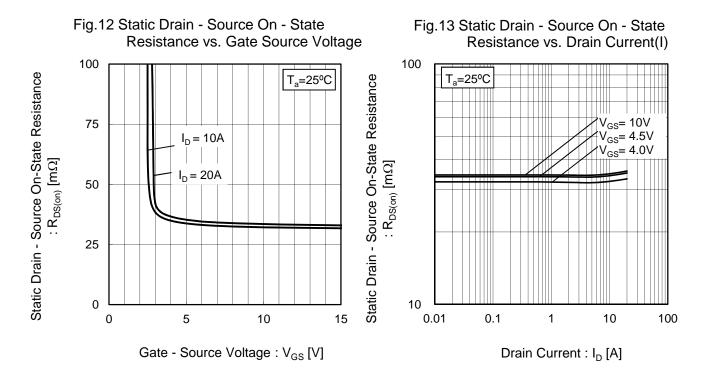
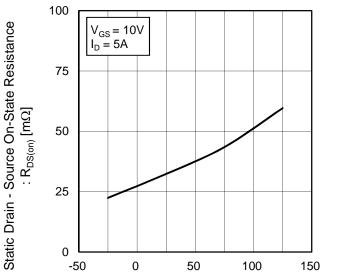


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



### • Electrical characteristic curves

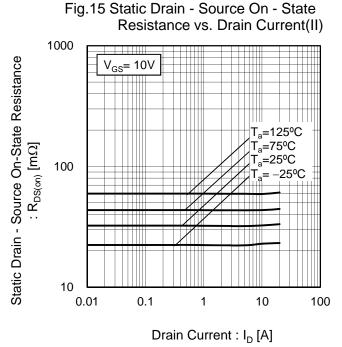
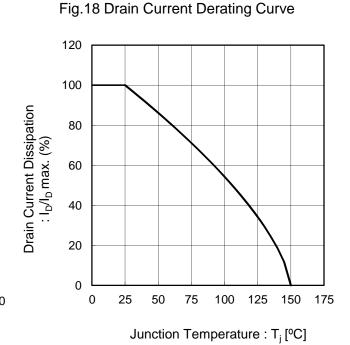


Fig.16 Static Drain-Source On-State
Resistance vs. Drain Current(III)

Ta=125°C
Ta=75°C
Ta=25°C
Ta=-25°C

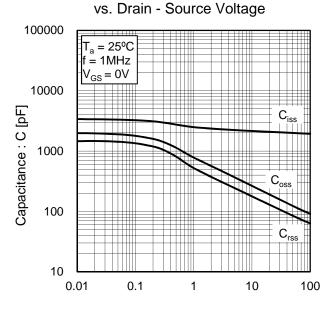
Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

1000  $V_{GS} = 4.0V$   $V_{GS} =$ 



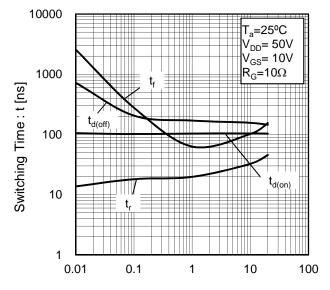
### • Electrical characteristic curves

Fig.19 Typical Capacitance



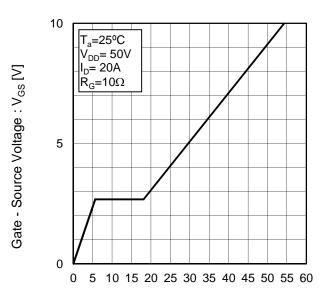
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.20 Switching Characteristics



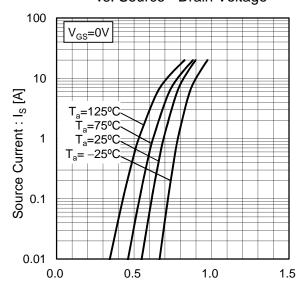
Drain Current : I<sub>D</sub> [A]

Fig.21 Dynamic Input Characteristics



Total Gate Charge : Q<sub>q</sub> [nC]

Fig.22 Source Current vs. Source - Drain Voltage

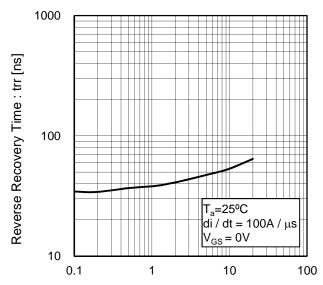


Source-Drain Voltage: V<sub>SD</sub> [V]

© 2015 ROHM Co., Ltd. All rights reserved.

### •Electrical characteristic curves

Fig23 Reverse Recovery Time vs.Source Current



Source Current : I<sub>S</sub> [A]

**Data Sheet** RSD201N10FRA

### ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

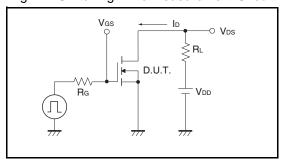


Fig.2-1 Gate Charge Measurement Circuit

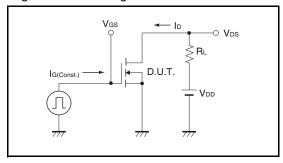


Fig.3-1 Avalanche Measurement Circuit

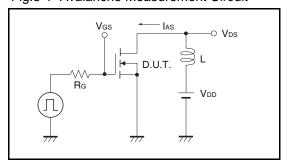


Fig.1-2 Switching Waveforms

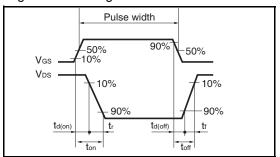


Fig.2-2 Gate Charge Waveform

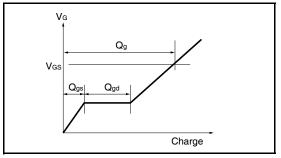
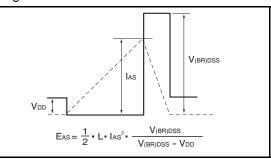
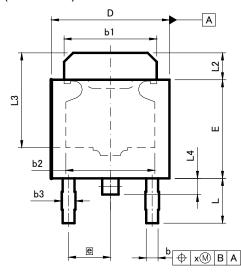


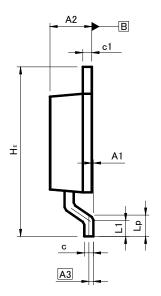
Fig.3-2 Avalanche Waveform

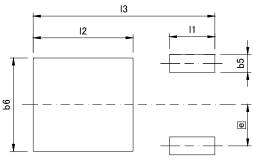


### ●Dimensions (Unit : mm)









DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0	0.006
A2	2.20	2.50	0.087	0.098
A3	0.:	25	0.0	01
b	0.55	0.75	0.022	0.03
b1	5.00	5.30	0.197	0.209
b2	5.0	00	0.:	20
b3	0.	75	0.0	03
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
Е	5.40	5.80	0.213	0.228
е	2.	30	0.0	09
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.11
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.30		0.209	
L4	0.9	90	0.0	35
Lp	1.00	1.60	0.039	0.063
х	_	0.25	_	0.01

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b5	_	1.00	_	0.04
b6	_	5.20	-	0.205
11	-	2.50	-	0.098
12	-	5.50	-	0.217
13	_	10.00	_	0.394

Dimension in mm/inches

## **Notice**

#### **Precaution on using ROHM Products**

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

Ì	JÁPAN	USA	EU	CHINA
Γ	CLASSⅢ	CL ACCIII	CLASS II b	CI VCCIII
Γ	CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

### **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### **Precaution for Foreign Exchange and Foreign Trade act**

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

#### **Precaution Regarding Intellectual Property Rights**

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
- 2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
- 3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

#### **Other Precaution**

- 1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

Notice-PAA-E Rev.001

#### **General Precaution**

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
- 3. The information contained in this doc ument is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in an y way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

**Notice – WE** © 2015 ROHM Co., Ltd. All rights reserved. Rev.001



# RSD201N10FRA - Web Page

Part Number	RSD201N10FRA
Package	CPT3
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes